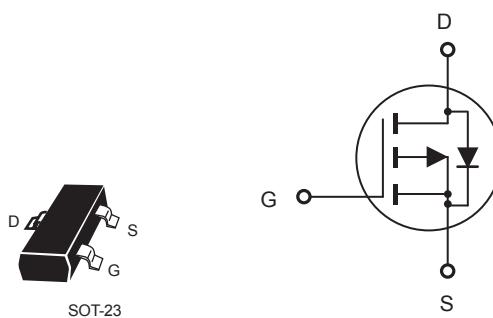


## FEATURES

- -30V, -3.8A,  $R_{DS(ON)} = 55m\Omega$  @ $V_{GS} = -10V$ .  
 $R_{DS(ON)} = 86m\Omega$  @ $V_{GS} = -4.5V$ .
- High dense cell design for extremely low  $R_{DS(ON)}$ .
- Rugged and reliable.
- Lead free product is acquired.
- SOT-23 package.



## ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-3.8	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	-15.2	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating and Store Temperature Range	$T_J, T_{Stg}$	-55 to 150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	100	$^\circ C/W$

# CES2313A

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$			-1	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>c</sup></b>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = -250\mu\text{A}$	-1		-3	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = -10\text{V}, I_D = -3.8\text{A}$		45	55	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -3\text{A}$		66	86	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>d</sup></b>						
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = -15\text{V}, I_D = -3.8\text{A}$		4		S
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		640		pF
Output Capacitance	$C_{\text{oss}}$			135		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			95		pF
<b>Switching Characteristics<sup>d</sup></b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = -15\text{V}, I_D = -1\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GEN}} = 6\Omega$		11	20	ns
Turn-On Rise Time	$t_r$			5	10	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			30	60	ns
Turn-Off Fall Time	$t_f$			7	14	ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = -15\text{V}, I_D = -3.8\text{A}, V_{\text{GS}} = -10\text{V}$		13	17	nC
Gate-Source Charge	$Q_{\text{gs}}$			2		nC
Gate-Drain Charge	$Q_{\text{gd}}$			3		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				-3.8	A
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = -3.8\text{A}$			-1.3	V

**Notes :**

- a.Repetitive Rating : Pulse width limited by maximum junction temperature.
- b.Surface Mounted on FR4 Board,  $t < 5 \text{ sec}$ .
- c.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- d.Guaranteed by design, not subject to production testing.